

TI Design - TIDA-00250

Bill of Materials

Comment	Description	Designator	Footprint	LibRef	Quantity
Printed Circuit Board	Printed Circuit Board	!PCB		PCB	1
06033C104KAT2A	CAP, CERM, 0.1uF, 25V, +/	C1, C2, C6, C8	0603	06033C104KAT2A	4
C1608X5R0J105K	CAP, CERM, 1uF, 6.3V, +/-	C3, C9	0603	C1608X5R0J105K	2
C0603C681K5RACTU	CAP, CERM, 680pF, 50V, +	C4, C5	0603	C0603C681K5RACTU	2
GRM188R60J106ME47D	CAP, CERM, 10uF, 6.3V, +/	C7	0603	GRM188R60J106ME47D	1
1N4148W-7-F	Diode, Ultrafast, 100V, 0.15	D1, D2, D3, D4, D5, D6	SOD-123	1N4148W-7-F	6
Fiducial	Fiducial mark. There is not	FID1, FID2, FID3	Fiducial10-20	Fiducial	3
NY PMS 440 0025 PH	Machine Screw, Round, #4-	H1, H2, H3, H4	NY PMS 440 0025 PH	NY PMS 440 0025 PH	4
1902C	Standoff, Hex, 0.5"L #4-40	H5, H6, H7, H8	Keystone_1902C	1902C	4
SSW-110-23-F-S	Connector, Receptacle, 100	J1, J2	CONN_SSW-110-23-F-S	SSW-110-23-F-S	2
HEADER_1X2	Header, Male 2-pin, 100mil	J3, J4	HDR100_1X2	HEADER_1X2	2
DT_Sensor		J5, J6	DT_Sensor	Component_1	2
Size: 0.65" x 0.20 "	Thermal Transfer Printable	LBL1	Label_650x200	THT-14-423-10	1
CRCW0603100KFKEA	RES, 100k ohm, 1%, 0.1W,	R1, R3, R5, R7, R12, R13,	0603	CRCW0603100KFKEA	8
CRCW060310K0JNEA	RES, 10k ohm, 5%, 0.1W,	R2, R6, R10, R11	0603	CRCW060310K0JNEA	4
CRCW060351K0JNEA	RES, 51k ohm, 5%, 0.1W,	R4, R14	0603	CRCW060351K0JNEA	2
CRCW0603200MJPEAHR	RES, 200M ohm, 5%, 0.1W	R8, R9	0603	CRCW0603200KJNEA	2
CRCW06030000Z0EA	RES, 0 ohm, 5%, 0.1W, 060	R17, R18, R19, R20	0603	CRCW06030000Z0EA	4
5002	Test Point, TH, Miniature, W	TP3, TP4, TP5, TP6	Keystone5002	5002	4
OPA2337_DCN_8	Imported	U1, U2, U5	DCN8	OPA2337_DCN_8	3

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